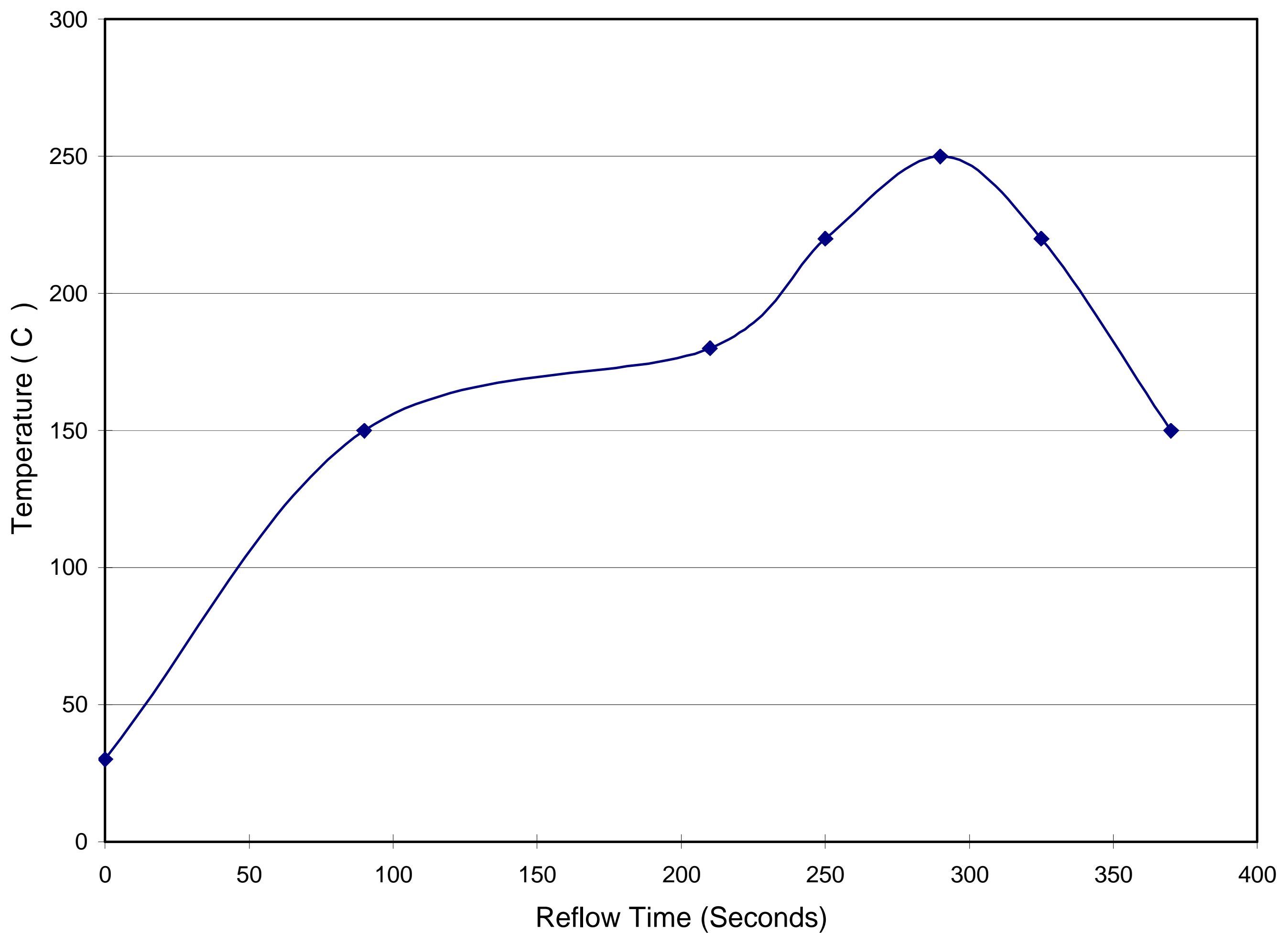
Soldering Profil for DCDC-Converter from TP

AN101

2008/10/08

Soldering Materials: Sn/Cu/ Ni

RECOMMENDED REFLOW SOLDERING PROFIL



1. Ramp up rate during preheat : 1.33 °c/Sec (From 30°C to 150°C)
2. Soaking temperature : 0.29 °C /Sec (From 150°C to 180°C)
3. Peak temperature : 250°C, above 220°C 40 to 70 sec
4. Ramp up rate during cooling : -1.56 °C /Sec (From 220°C to 150°C)

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Soldering Profil for DCDC-Converter from TP

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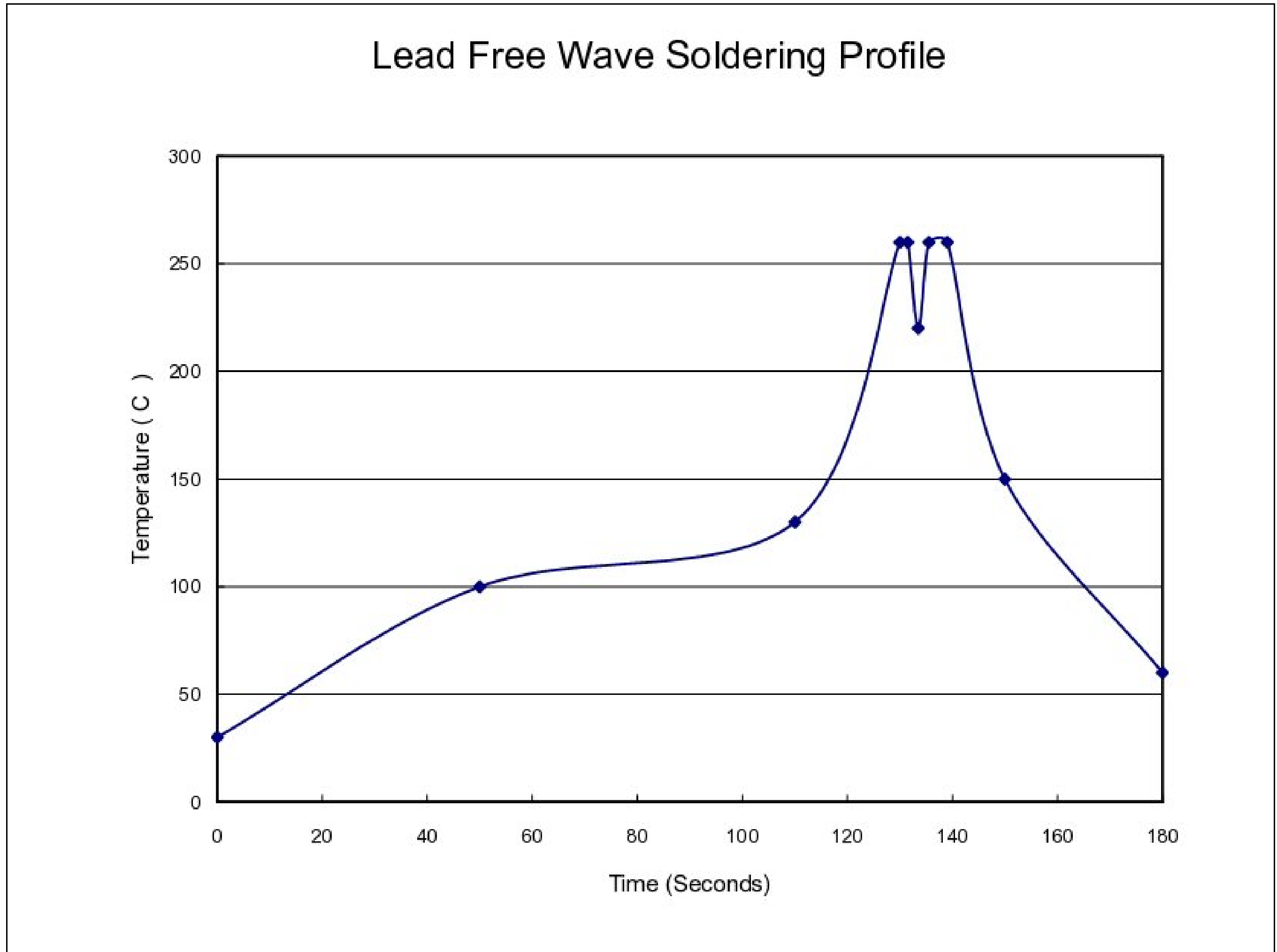
RECOMMENDED WAVE SOLDERING PROFIL



1. Soaking temperature : 1.4 °C /Sec (From 50°C to 100°C)
2. Ramp up rate during reflow : 0.5 °C /Sec (From 100°C to 130°C) 60±20sec
3. Peak temperature : 260°C, above 250°C 3 to 6 sec
4. Ramp up rate during cooling : -10 °C /Sec (From 260°C to 150°C)

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